MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOIC4 W
CASE 751EP
ISSUE 0

OPTION B - NO BEVEL EDGE PRESENT,
HALF MOON [CRESCENT] PRESENT

OPTION A - BEVEL EDGE PRESENT

LAND PATTERN RECOMMENDATION

NOTES: UNLESS OTHERWISE SPECIFIED
A. THIS PACKAGE DOES NOT CONFORM TO
JEDEC TO269AA
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS,
MOLD FLASH AND TIE BAR EXTRUSIONS.
D. DIMENSIONS AND TOLERANCES AS PER ASME
Y14.5-2009.
E. LAND PATTERN AS PER IPC7351# SOIC254P960X400-4N

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